BST-505 Bga Solder Ball Size For Micro Welding Mobile Phone Repair Tools Soldering Ball Diameter 0.2mm-0.65mm

PRODUCT DISPLAY

PRODUCT DETAILS


0.2mm


0.25mm


0.3mm


0.35mm


0.4mm


0.45mm


0.5mm


0.55mm


0.6mm


0.65mm

A bottle of 25,000

PRODUCT PHOTOGRAPH

Brand:	BST	Name:	solder ball
Ingredients:	alloy:Sn63/Pb37	Size:	16*35mm
Specifications:	0.2mm (55.4g/10bottle), 0.25mm (68.5G/10bottle), 0.3mm (65.8G/10bottle), 0.35mm (74G/10bottle), 0.4mm (86.3G/10bottle), 0.45mm (100.8 G/10bottle), 0.5mm (119.7G/bottle10), 0.55mm (142.7G/10bottle), 0.6mm (167.7G/10bottle)		
Quantity:	25,000 / bottle		
Features:	Tin ball is mainly connected to semiconductor wafers and circuit		
	boards and PCB boards, and small ball type tin electronic parts that transmit electronic signals.